

1 ABSTRACT OF THE DISCLOSURE

2 The present invention includes an electronic device workpiece
3 processing apparatus and method of communicating signals within an
4 electronic device workpiece processing apparatus. One embodiment of
5 an electronic device workpiece processing apparatus includes a chuck
6 including a surface, an electrical coupling adjacent the surface, and
7 electrical interconnect configured to connect with the electrical coupling
8 of the chuck and conduct a signal within the chuck; an intermediate
9 member having a first surface and a second surface and the
10 intermediate member including: an electrical coupling adjacent the first
11 surface and configured to couple with the electrical coupling of the
12 chuck; an electrical coupling adjacent the second surface; and an
13 electrical interconnect configured to connect the electrical coupling
14 adjacent the first surface and the electrical coupling adjacent the second
15 surface; and an electronic device workpiece configured to couple with
16 the second surface of the intermediate member, the electronic device
17 workpiece including a sensor and an electrical coupling configured to
18 provide electrical connection of the sensor with the electrical coupling
19 of the second surface of the intermediate member.